

ABSTRACT

There is provided a Cu-Al binary alloy sputtering target with a high Al content while suppressing occurrence of cracks on the sputtering target, and a method for manufacturing the same. A sputtering target is composed of a sintered body containing a binary alloy of Cu and Al, the rest being inevitable impurities, wherein a content (at%) of Cu and Al satisfies a relational expression of $0.48 \leq \text{Al} / (\text{Cu} + \text{Al}) \leq 0.70$, and wherein a relative density is 95% or more.